

**Assembly Transfer of Non-Automotive MEMS in LCC, CBGA and LCC_V Packages to
Cirtek Electronic Corporation**

Qualification Plan for LCC Package at Cirtek

QUALIFICATION PLAN			
TEST	SPECIFICATION	SAMPLE SIZE	COMPLETION DATE
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	September 2017
Group D	MIL-STD-883, M5005	3 x 15	September 2017
Random Drop	AEC-Q100 Test G5	1 x 5	September 2017
Solderability	JEDEC <i>JESD22-B102</i>	1 x 15	September 2017
High Temperature Storage (HTS)	JEDEC <i>JESD22-A103</i>	1 x 77	September 2017

*Preconditioning per JEDEC/IPC J-STD-020

Qualification Plan for CBGA Package at Cirtek

QUALIFICATION PLAN			
TEST	SPECIFICATION	SAMPLE SIZE	COMPLETION DATE
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	September 2017
Group D	MIL-STD-883, M5005	3 x 15	September 2017
Guided Drop	IEC 60068-2-32	1 x 5	September 2017
Mechanical Shock - Powered	IEC 60068-2-27	3 x 10	September 2017
High Temperature Storage (HTS)	JEDEC <i>JESD22-A103</i>	1 x 77	September 2017
Electrostatic Discharge <i>Field Induced Charge Device Model</i>	JEDEC <i>JESD22-C101</i>	3/voltage	September 2017

*Preconditioning per JEDEC/IPC J-STD-020

**Assembly Transfer of Non-Automotive MEMS in LCC, CBGA and LCC_V Packages to
Cirtek Electronic Corporation**

Qualification Plan for LCC_V Package at Cirtek

QUALIFICATION PLAN			
TEST	SPECIFICATION	SAMPLE SIZE	COMPLETION DATE
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	December 2017
Group D	MIL-STD-883, M5005	1 x 15	December 2017
Guided Drop Test	AEC-Q100 Test G5	1 x 5	December 2017
Mechanical Shock - Powered	IEC 60068-2-27	3 x 10	December 2017
Solderability	JEDEC <i>JESD22-B102</i>	1 x 15	December 2017
High Temperature Storage (HTS)	JEDEC <i>JESD22-A103</i>	1 x 77	December 2017
Electrostatic Discharge <i>Field Induced Charge Device Model</i>	JEDEC <i>JESD22-C101</i>	3/voltage	December 2017

*Preconditioning per JEDEC/IPC J-STD-020